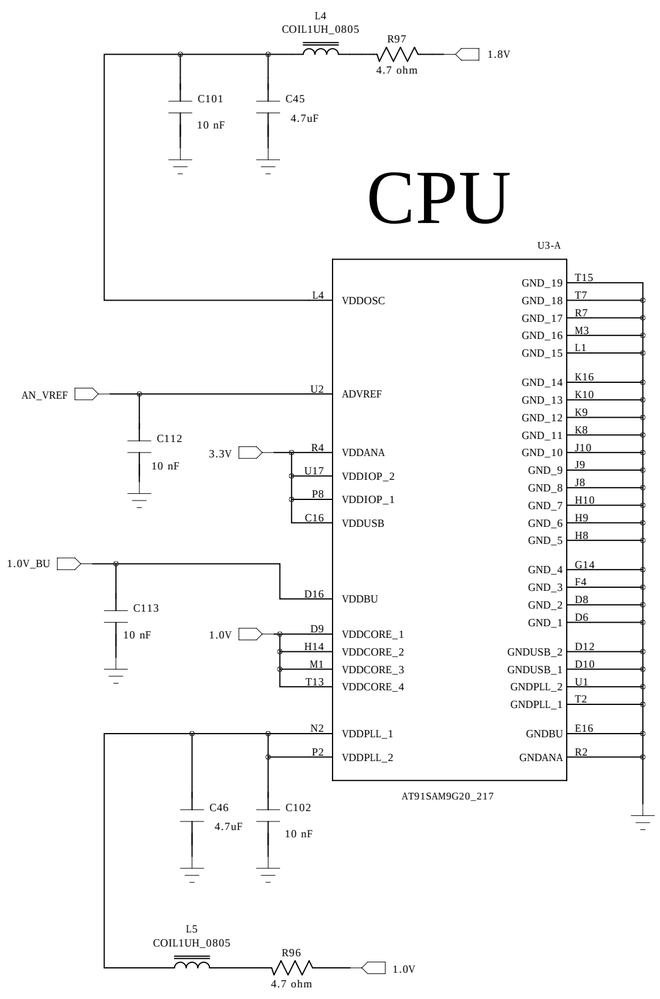
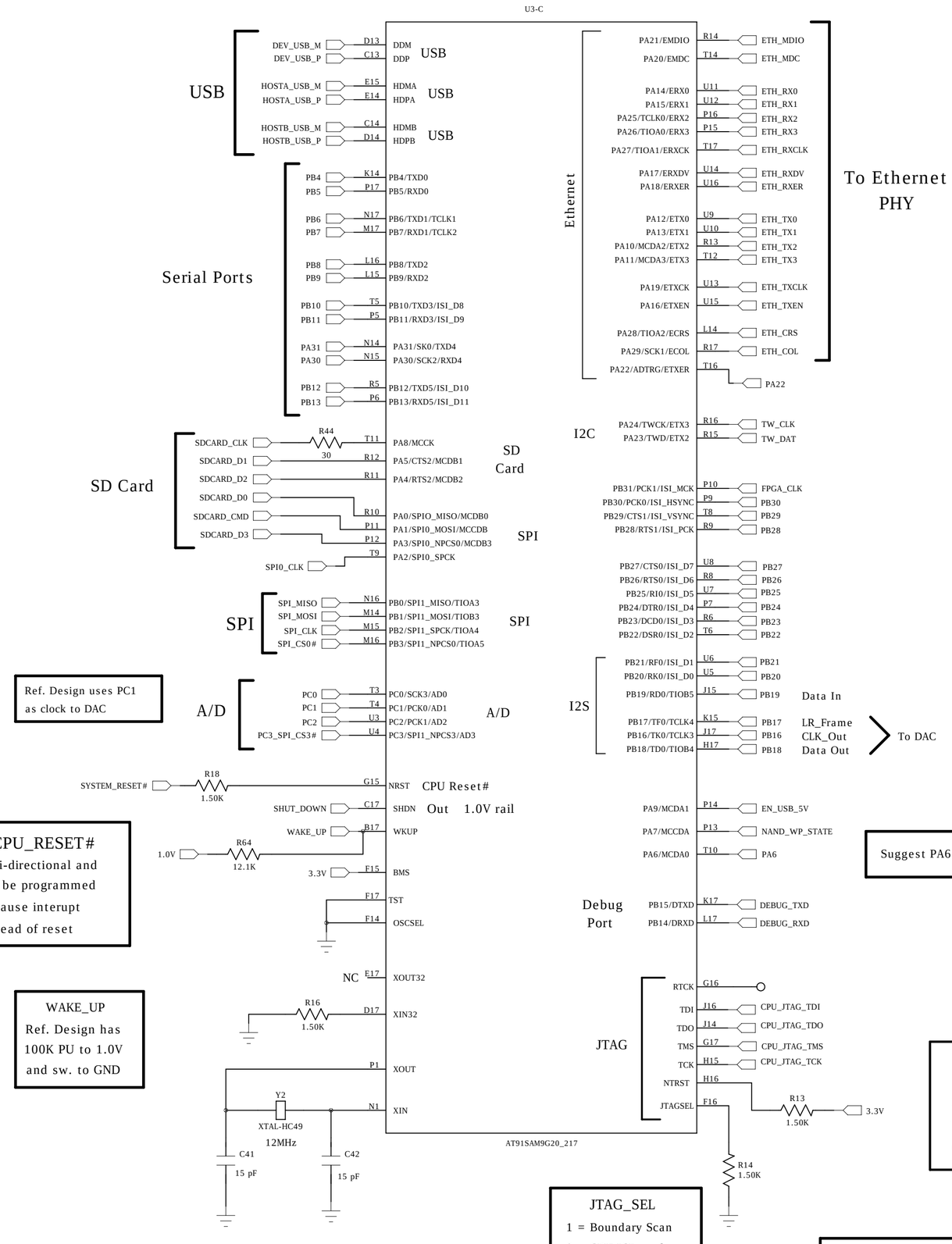
TS-4200 Rev B

CPU

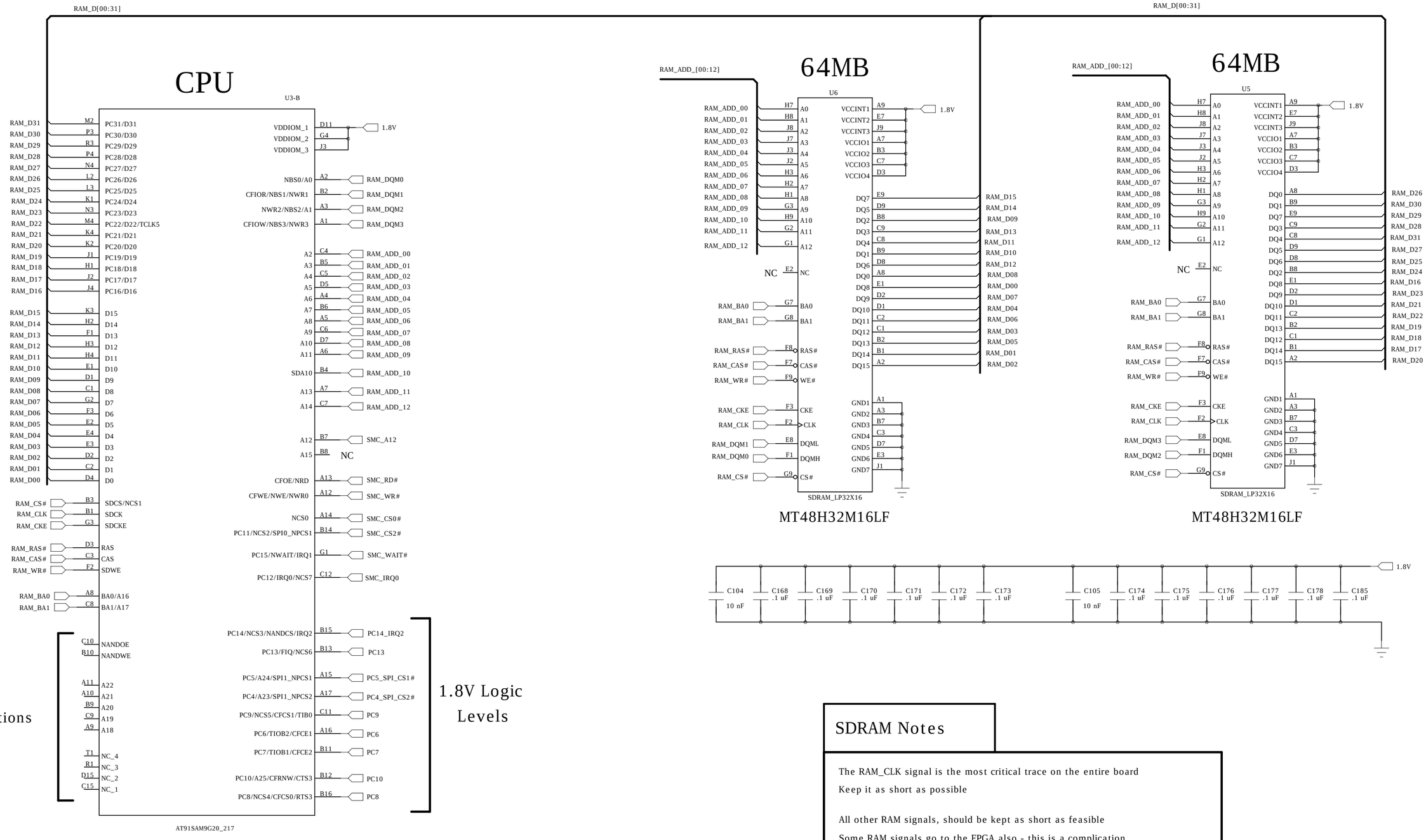


CPU



Technologic Systems	Date Oct. 19, 2011	
Title: TS-4200 CPU		
Rev: D	Designer	Sheet 1 of 7

128 MB RAM



SDRAM Notes

The RAM_CLK signal is the most critical trace on the entire board
Keep it as short as possible

All other RAM signals, should be kept as short as feasible
Some RAM signals go to the FPGA also - this is a complication

RAM data signals can be swapped bit-wise or byte-wise
For example, D16-D23 can be swapped with D24-D31
This would require the respective DQMx lines to be swapped as well

Bit-wise swaps are allowed within a byte
For example, D2 and D5 can be swapped

Technologic Systems		Date Oct. 19, 2011
Title: TS-4200 RAM		
Rev: D	Designer RLM	Sheet 2 of 7

A3P125 has:

3000 Tiles (about 1200 LUTs)

4 Kbytes total of Block RAM

97 I/O with 144 pin package

"true instant ON"

Input PLL clock = 1.5 MHz min

FPGA

When SYSTEM_RESET# asserted, then set these as follows:

Asserted:

- OFF_BD_RST#
- EN_SDCARD_PWR#
- RED_LED#
- GREEN_LED#

Deasserted:

- EN_ETH_PWR#
- REBOOT
- NVRAM_CS
- NAND_CS#

When SYSTEM_RESET# deasserted, Latch BUS_ALE# and BUS_RD# into a register

Early Boot code should deassert OFF_BD_RST# signal. (after SPI Flash loaded into RAM)

Boot Straps

Mode 2	Boots from
1	NAND Flash
0	SD Card

BUS_ALE# = MODE1

BUS_RD# = MODE2

Warning: MUX_AD00 thru AD07 is used by NAND Flash

Devices connected to this bus must never drive it when BUS_RD# is deasserted (must be off within 30 nS of deassertion)

Devices must pull the BUS_WAIT# line low if they need more than 150 nS strobe

FPGA_CLK = CPU Timer Out

DIO_09 = Push_switch

All NVRAM interface signals must be kept in low state when not accessing NVRAM

Inputs with 1.8V rail have diode clamp to 1.8V

REBOOT high causes all power rails to go low for 200 mS

RED_LED# and GREEN_LED# must be Open Drain

To CPU Address/Data Bus

MUX_AD[00:15]

RAM_D[00:31]

3.3V

1.8V

U4-A

MUX_AD00	D5	GAC0/IO04RSB0	IO115RSB1	J2	RAM_D00	
MUX_AD01	D9	GBB2/IO43RSB0	IO128RSB1	D1	RAM_D01	
MUX_AD02	C10	GBA2/IO41RSB0	IO127RSB1	F4	RAM_D02	
MUX_AD03	E8	GCC1/IO51RSB0	IO129RSB1	D2	RAM_D03	
MUX_AD04	C5	IO10RSB0	IO100RSB1	K5	RAM_D04	
MUX_AD05	D6	GAC1/IO05RSB0	GFB0/IO123RSB1	F1	RAM_D05	
MUX_AD06	B9	GBB0/IO37RSB0	IO98RSB1	K6	RAM_D06	
MUX_AD07	A9	IO25RSB0	GFC0/IO125RSB1	E2	RAM_D07	
MUX_AD08	K11	GDA0/IO66RSB0	GAA2/IO67RSB1	D4	RAM_D08	
MUX_AD09	K12	GDB0/IO64RSB0	IO68RSB1	E5	RAM_D09	
MUX_AD10	G8	GDC1/IO61RSB0	IO130RSB1	D3	RAM_D10	
MUX_AD11	F9	GCB0/IO54RSB0	IO116RSB1	J5	RAM_D11	
MUX_AD12	F8	GCC0/IO52RSB0	GDB2/IO71RSB1	H8	RAM_D12	
MUX_AD13	C9	IO27RSB0	GFC1/IO126RSB1	E3	RAM_D13	
MUX_AD14	D8	GBC1/IO36RSB0	GDA2/IO70RSB1	J9	RAM_D14	
MUX_AD15	D7	GBC0/IO35RSB0	IO117RSB1	J6	RAM_D15	
BUS_ALE#	G9	IO48RSB0	GEB1/IO110RSB1	J1	RAM_DQM0	A0/Low Byte En.
BUS_DIR	H11	IO49RSB0	GFC2/IO118RSB1	H3	RAM_DQM1	High Byte Enable
BUS_CS#	G10	GCC2/IO59RSB0	GEB0/IO109RSB1	K1	RAM_DQM2	Address 1
BUS_BHE#	C11	IO42RSB0	GEC1/IO112RSB1	H4	RAM_ADD_00	Address 2
FPGA_CLK	D10	IO28RSB0	GAC2/IO131RSB1	C3	RAM_ADD_01	Address 3
OFF_BD_RST#	H7	IO60RSB0	GFA1/IO121RSB1	G1	RAM_ADD_02	Address 4
EN_SDCARD_PWR#	H6	IO50RSB0	GFB2/IO119RSB1	H2	RAM_ADD_03	Address 5
PB31	J11	GDA1/IO65RSB0	GEA1/IO108RSB1	K2	RAM_ADD_04	Address 6
DIO_00	A11	GBA1/IO40RSB0	GEC0/IO111RSB1	J4	RAM_ADD_05	Address 7
DIO_01	B10	GBB1/IO38RSB0	GEC2/IO104RSB1	M2	RAM_ADD_06	Address 8
DIO_02	A10	GBA0/IO39RSB0	IO132RSB1	C1	RAM_ADD_07	Address 9
DIO_03	B5	IO08RSB0	GEA2/IO106RSB1	K4	RAM_ADD_08	Address 10
DIO_04	A4	GAB1/IO03RSB0	IO103RSB1	M3	RAM_ADD_09	Address 11
DIO_05	B4	GAA1/IO01RSB0	GEA0/IO107RSB1	K3	SMC_A12	Address 12
DIO_06	A3	GAB0/IO02RSB0	IO101RSB1	M4	RAM_ADD_11	Address 13
DIO_07	B3	GAA0/IO00RSB0	IO95RSB1	L6	SMC_IRQ0	
DIO_08	A5	IO11RSB0	GFA0/IO122RSB1	G4	SMC_WAIT#	
DIO_09	C6	IO12RSB0	IO94RSB1	M6	SMC_RD#	
DIO_10	B6	IO14RSB0	IO97RSB1	M5	SMC_WR#	
DIO_11	A7	IO18RSB0	IO74RSB1	L8	SMC_CS0#	
DIO_12	B7	IO19RSB0			SMC_CS2#	
DIO_13	C7	IO21RSB0	IO75RSB1	M8		
DIO_14	B8	IO22RSB0			R80 4.75K	PB4 UART0_TXD
DIO_15	C8	IO24RSB0	Input GEB2/IO105RSB1	L3		
EN_ETH_POWER#	J12	GDB1/IO63RSB0	Input GFA2/IO120RSB1	C2	R79 4.75K	SYSTEM_RESET#
BUS_WAIT#	H9	GDC0/IO62RSB0	Input IO102RSB1	L4	512HZ	
NVRAM_CS	G12	GCB2/IO58RSB0	Out IO85RSB1	L7	REBOOT	
NVRAM_MISO	G11	IO47RSB0	Input IO86RSB1	M7	POWER_FAIL#	
NVRAM_MOSI	F11	GCA1/IO55RSB0	Input GFB1/IO124RSB1	F3	NAND_BUSY#	
NVRAM_CLK	F12	GCA2/IO57RSB0	Input GAB2/IO69RSB1	B1		
NAND_CLE	D12	GCB1/IO53RSB0	Out GDC2/IO72RSB1	K9	GREEN_LED#	
NAND_ALE	D11	IO44RSB0	Out IO73RSB1	K8	RED_LED#	
NAND_RD#	E12	IO46RSB0				
NAND_WR#	C12	GBC2/IO45RSB0				
NAND_CS#	E11	GCA0/IO56RSB0				
FPGA_JTAG_TDO	J10	TDO				
FPGA_JTAG_TMS	L9	TMS				
FPGA_JTAG_TDI	M9	TDI				
FPGA_JTAG_TCK	J8	TCK				
3.3V	L12	TRST				

A3P125_FG144

DIO_[00:15]

R61 12.1K, R62 12.1K, R63 12.1K

3.3V

200 Hz

R35 47.0K

U9

NC7SZ14

1.8V, 5 VCC, 4, 3 GND, NC 1, 2

C161 .1 uF

FPGA

RMCF 1/16S 10 5% R

1.5V — R98 4.7 ohm — L6 COIL1UH_0805 — LQM21FN1R0N

C100 10 nF

C44 4.7uF

U4-B

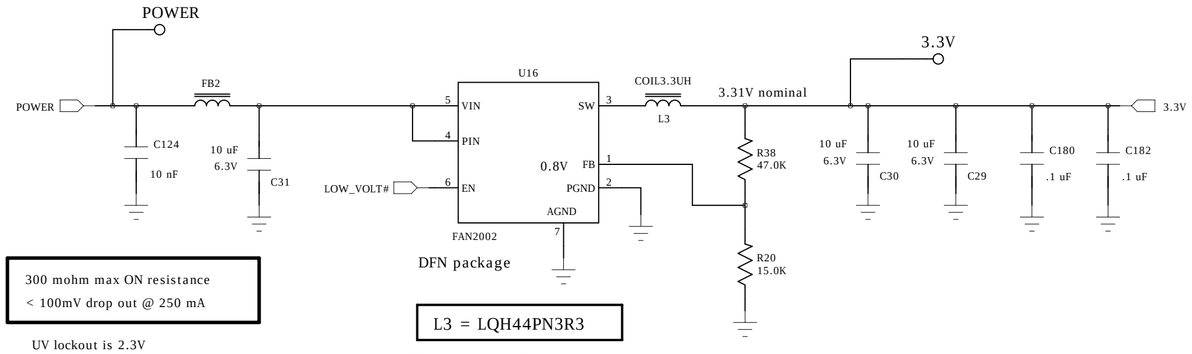
1.5V	A8	VCC_1	VCCPLF	G3	
	C4	VCC_2	VCOMPLF	F2	
	E1	VCC_3	GND_1	A6	
	E10	VCC_4	GND_2	B2	
	H1	VCC_5	GND_3	B11	
	H5	VCC_6	GND_4	F5	
	H12	VCC_7	GND_5	F6	
	J7	VCC_8	GND_6	F7	
1.8V	E4	VCCIB1_1	GND_7	F10	
	J3	VCCIB1_2	GND_8	G2	
	L5	VCCIB1_3	GND_9	G5	
	M10	VCCIB1_4	GND_10	G6	
	L2	VMV1_1	GND_11	G7	
	L11	VMV1_2	GND_12	K7	
3.3V	E6	VCCIB0_1	GND_13	K10	
	E7	VCCIB0_2	GND_14	L1	
	E9	VCCIB0_3	GNDQ_1	A1	
	H10	VCCIB0_4	GNDQ_2	A12	
	A2	VMV0_1	GNDQ_3	M1	
	B12	VMV0_2	GNDQ_4	M12	
	M11	VPUMP			
	L10	VJTAG			

A3P125_FG144

1.8V — C197 .1 uF, C198 .1 uF, C128 10 nF, C129 10 nF

Technologic Systems		Date	Oct. 19, 2011
Title:	TS-4200 FPGA		
Rev: D	Designer	Sheet	3 of 7

3.3V Supply

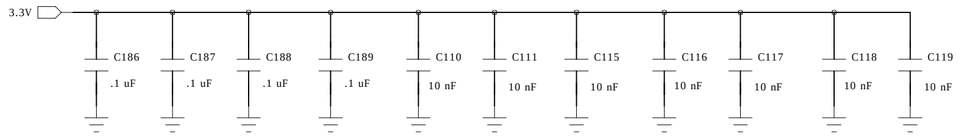


300 mohm max ON resistance
< 100mV drop out @ 250 mA

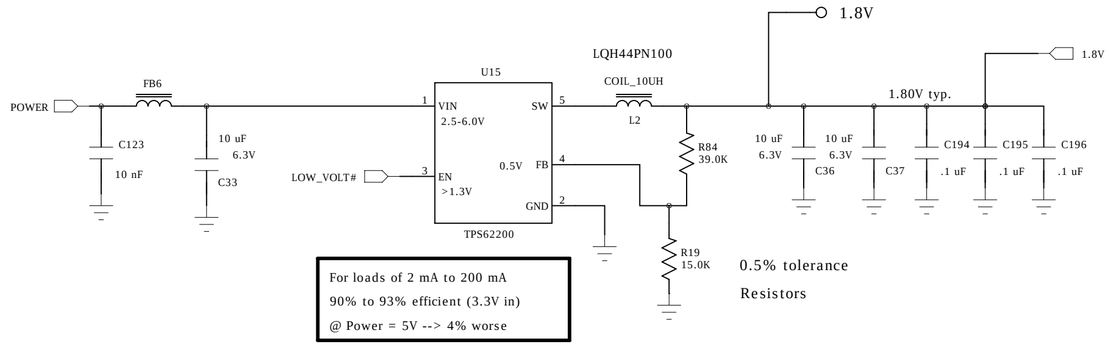
UV lockout is 2.3V

L3 = LQH44PN3R3

Max. current = 1.7 Amps



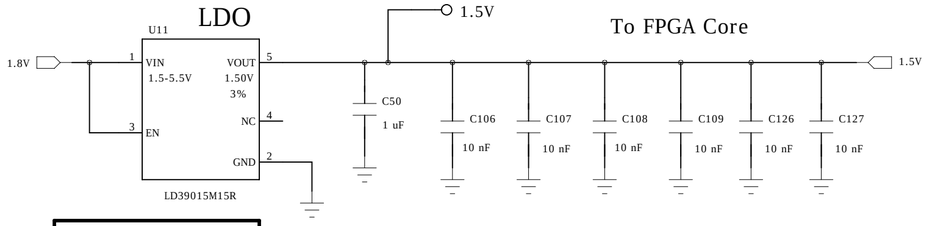
1.8V Supply



For loads of 2 mA to 200 mA
90% to 93% efficient (3.3V in)
@ Power = 5V --> 4% worse

0.5% tolerance
Resistors

1.5V Supply



150 mA max load
100mV drop out
stable with 1 uF ceramic
25 uS Turn-on

Power Sequence

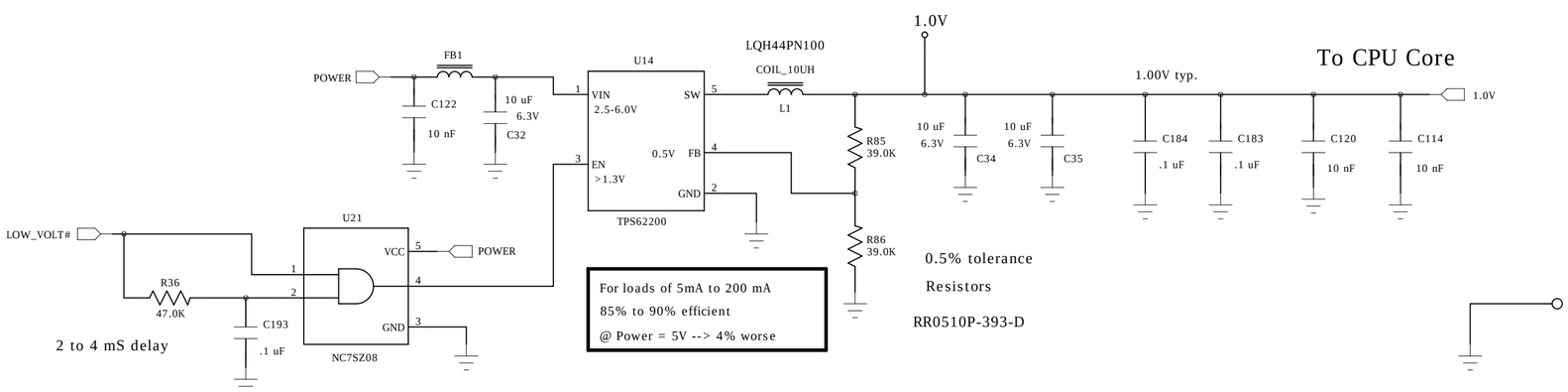
After power is first applied, or after a "Reboot"
All power rails are off for 200 mS then:

- the 3.3V and 1.8V are enabled
  these will reach 95% in about 800 uS
  (the 1.5V rail will ramp 25 uS delayed)

- Then 2-4 mS later, the 1.0V rail is enabled
  It also requires about 800 uS to ramp

CPU Reset# is asserted before 1.0V rail is enabled

1.0V Supply

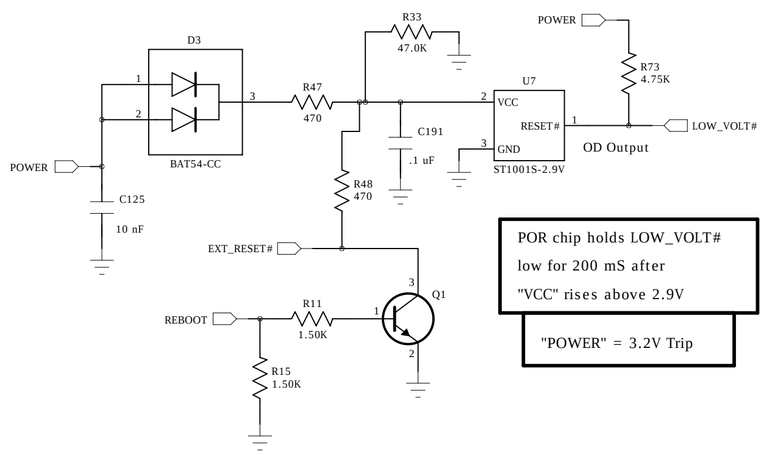


For loads of 5mA to 200 mA
85% to 90% efficient
@ Power = 5V --> 4% worse

0.5% tolerance
Resistors

RR0510P-393-D

POR

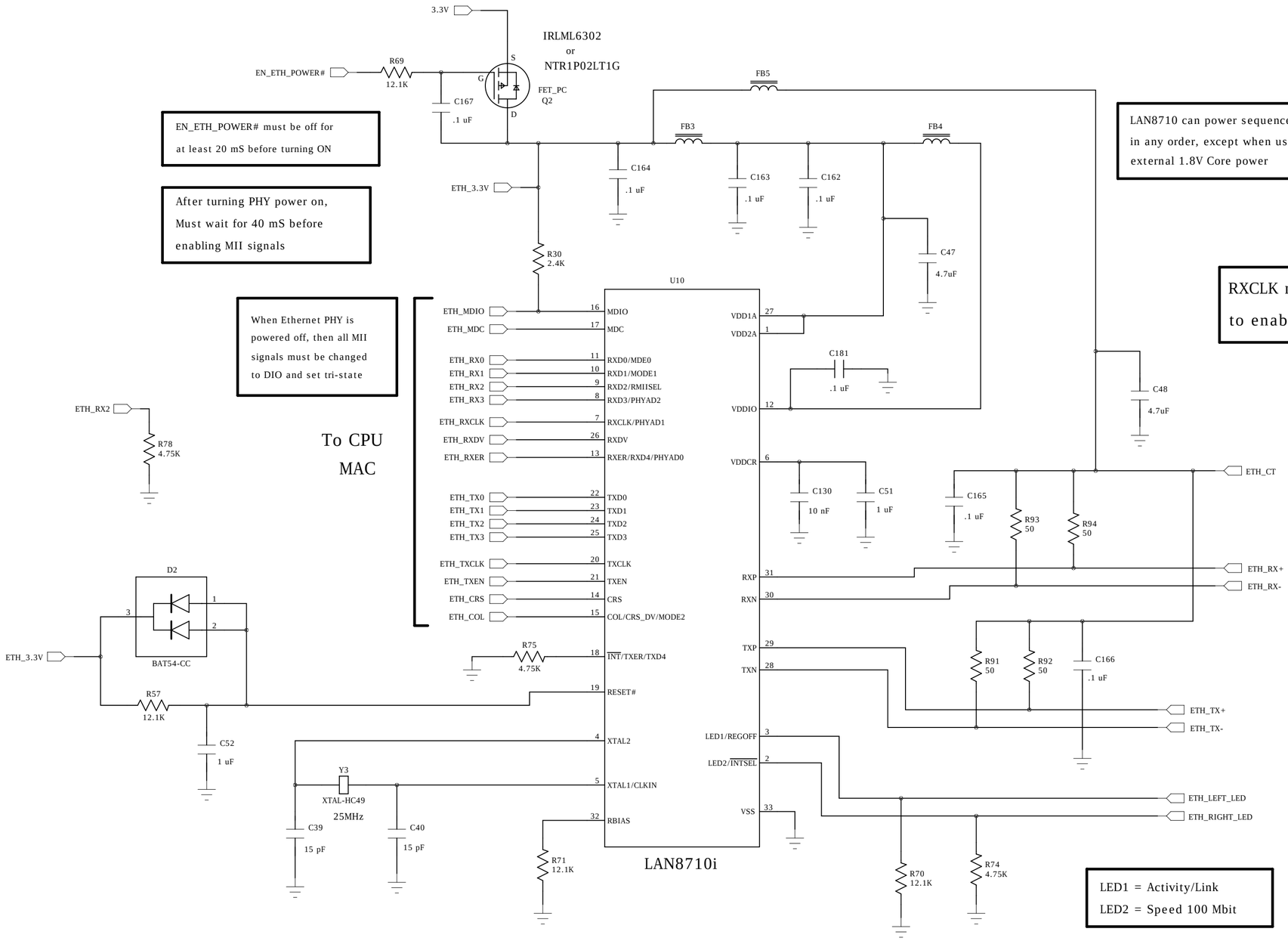


POR chip holds LOW_VOLT#
low for 200 mS after
"VCC" rises above 2.9V

"POWER" = 3.2V Trip

Technologic Systems	Date Oct. 19, 2011	
Title: TS-4200 Power Supplies and POR		
Rev: D	Designer RLM	Sheet 4 of 7

10/100 Ethernet



EN_ETH_POWER# must be off for at least 20 mS before turning ON

After turning PHY power on, Must wait for 40 mS before enabling MII signals

When Ethernet PHY is powered off, then all MII signals must be changed to DIO and set tri-state

To CPU MAC

LAN8710 can power sequence in any order, except when using external 1.8V Core power

RXCLK must be biased low to enable internal 1.8V reg.

LED1 = Activity/Link
LED2 = Speed 100 Mbit

Resistor PD on pin 18 is not required per data sheet
But Jesse could not get it to work until we added it

MDIO bus can not be used until 100 uS after Reset# is deasserted

MDCLK max is 2.5 MHz

Beware

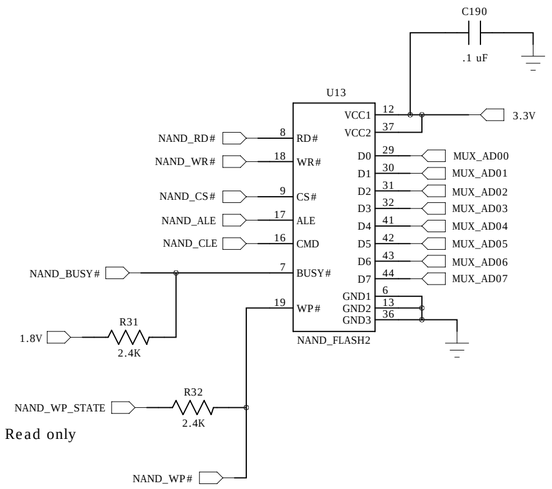
PHY PU and PD resistors are 67K ohm typical

CPU PU resistors are 70K typ. and 40K min.

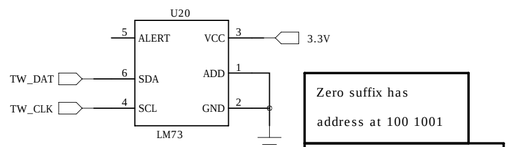
The PHY address is controlled by strapping pins. If CPU has PU; PHY has PD --> indeterminent

Technologic Systems	Date Oct. 19, 2011	
Title: TS-4200 Ethernet PHY		
Rev: D	Designer	Sheet 5 of 7

512 MB or 2 GB NAND Flash



Temp Sensor

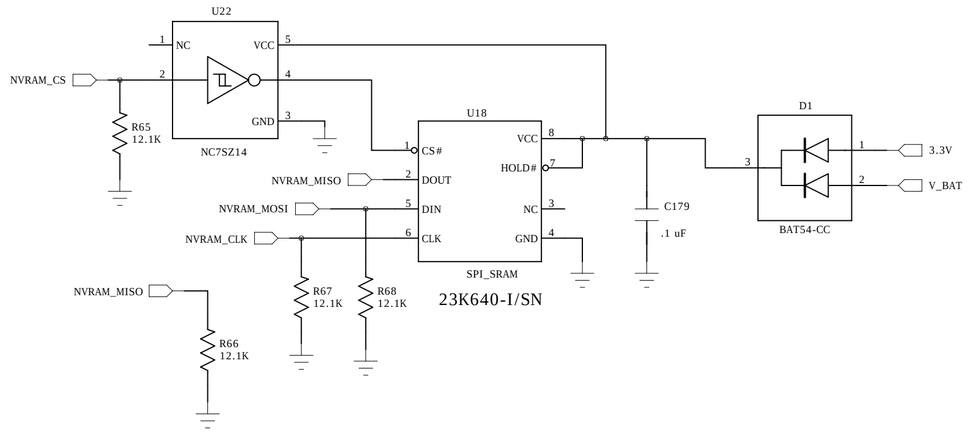


Zero suffix has
address at 100 1001

Best to Reset after
all power cycles

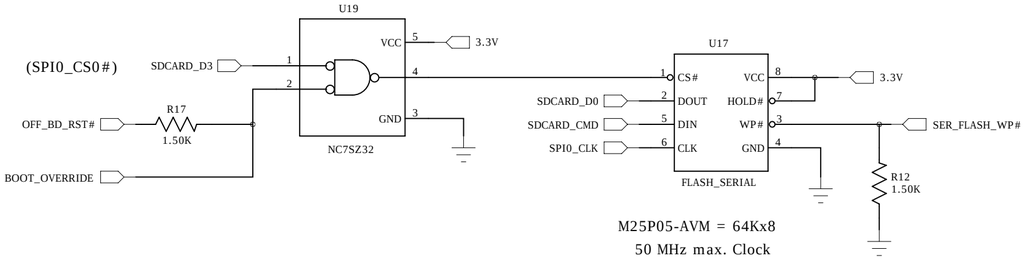
Set PD bit, Wait 50 mS
Then clear PD bit

8K Byte NVRAM

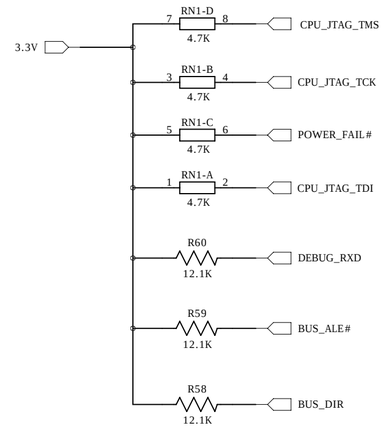


64KB Serial Boot Flash

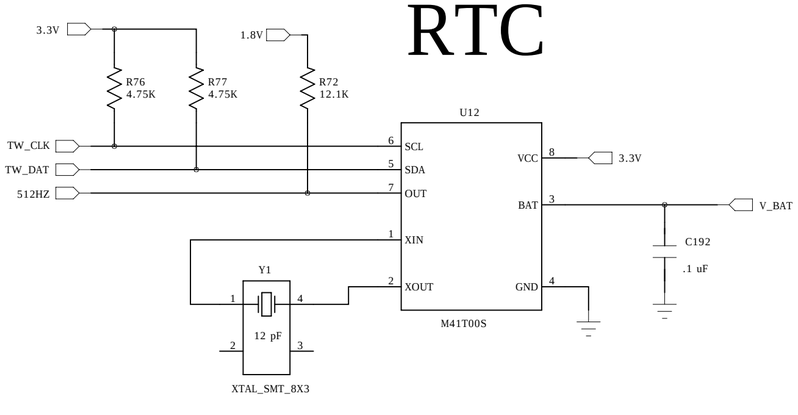
Boot using SPI0 Port



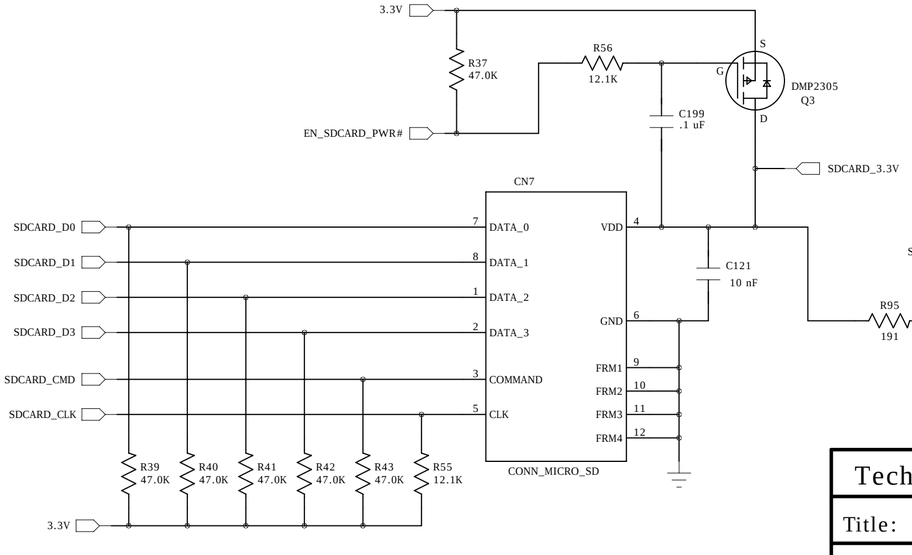
M25P05-AVM = 64Kx8
50 MHz max. Clock



RTC



Micro SD Card Socket



Time constant
= 47 mS

Technologic Systems	Date Oct. 19, 2011	
Title: TS-4200 Flash, NVRAM, RTC, Boot Flash		
Rev: D	Designer	Sheet 6 of 7

Two 100-pin Off-board Connectors

"POWER" pins supply all power to the module
Apply 3.6V to 5.5V to these pins

Current drain is 50mA to 400 mA

EXT_RESET# is an Input
used to reboot the CPU

CN2 pin 27 should be connected
to CN2 pin 33 on the base board

OFF_BD_RESET# is an Output
used to reset all peripherals

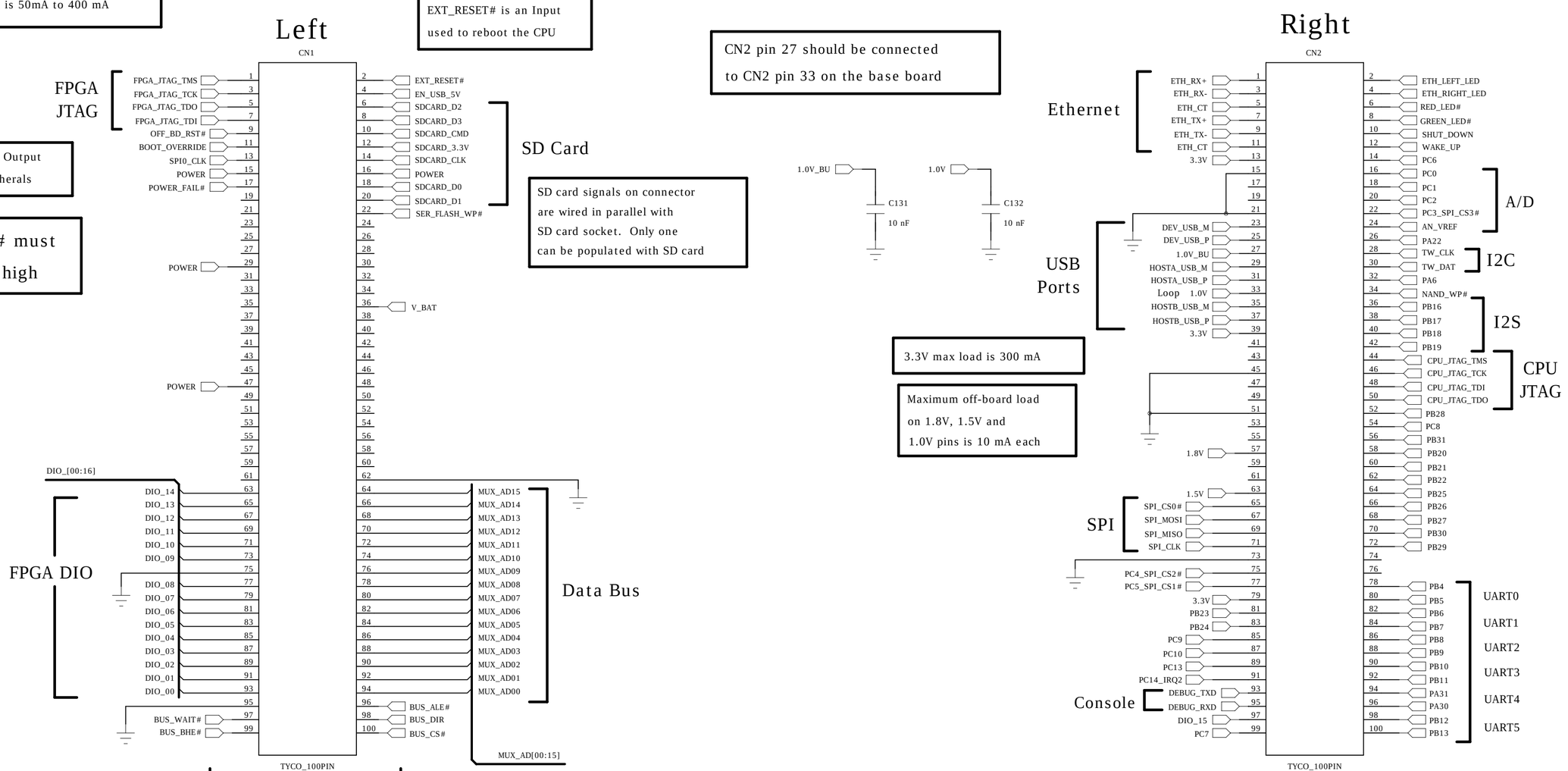
POWER_FAIL# must
not be driven high

SD card signals on connector
are wired in parallel with
SD card socket. Only one
can be populated with SD card

3.3V max load is 300 mA

Maximum off-board load
on 1.8V, 1.5V and
1.0V pins is 10 mA each

Max. load on JTAG_Vcc
(CN2-79) is 20 mA



Boot Strap

Mode 2	Boots from
1	NAND Flash
0	SD Card

BUS_DIR = MODE2

MODE1 and MODE2 states
are latched prior to
OFF_BD_RESET# deasserted

MODE1 and MODE2
have PU resistors

Use 1.5K ohm resistor
to "OFF_BD_RESET#"
to set Mode pins "low"

Devices connected to this bus must never
drive it when BUS_CS# is deasserted
(must be off within 30 nS of deassertion)

Devices must pull the BUS_WAIT# line low
if they need more than 150 nS strobe

The data bus can not have more than
30 pF of off-board capacitive loading
May need data buffer chip for heavy loads

BUS_ALE# = Address Latch Enable
BUS_BHE# = Byte High Enable (for 16-bit cycles)

If Bus is not needed, the following
can be changed to DIO:
- Bus Control signals
- MUX_AD08 thru 15

Bus cycles use 11 address lines
AD0 thru AD10
This provides 1K address space
for 8-bit bus cycles (000-3FF)
and 1K for 16-bit cycles (400-7FF)

These DIO have 1.8V levels
PC4, PC5, PC6
PC7, PC8, PC9
PC10, PC13, PC14

All other DIO uses 3.3V levels

Technologic Systems	Date Oct. 19, 2011	
Title: TS-4200 Off-board Connectors		
Rev: D	Designer	Sheet 7 of 7